

C5735

Conductor

Description

C5735 is a gold conductor paste that has been formulated for use with Au wire bonding applications. C5735 is a screen printable paste that gives an extremely dense and defect-free fired film. Fine lines are able to be printed down to 75 µm lines and spaces with etching possible for ultra-fine features down to 25 µm.

Key Features

- Excellent Au bondability High conductivity Fine line printing Etchable (Chemical and laser)



This picture does not show the packaging of C5735 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Conductivity	≤ 4.5 milliohms/square at 10 µm fired film thickness using 25 mil wide serpentine conductor pattern
Viscosity	300 – 530 Kcps, Anton Paar Physica MCR101, CP25-1, 4sec-1, 25 °C
Solids	84.5 ± 1 %
Alloy Ratio	100
Coverage	118 cm ² /g @ 10 µm fired film thickness
Metal	Au

Recommended Processing Guide

Printing Parameters	325 – 400 mesh stainless steel screen 0.3 – 0.5 mil emulsion 1.1 mil wire
Drying Temperature	150 °C for 10 minutes Make sure ventilation is sufficient to prevent the wet film from skinning
Process Temperature (TDS)	850 °C peak temperature, 10 minutes at peak Total cycle time of 45 – 60 minutes
Film Thickness	Wet: 22 – 28 µm Dry: 11 – 15 µm Fired: 6 – 10 µm
Recommended Thinner	RV-507
Paste Compatibility	IP9217, IP9227 multilayer dielectrics

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Warranty

6 months

Storage

Refrigerate at 1 – 5°C to ensure shelf life. Allow paste to come to room temperature prior to opening. Spatulate well before using, as settling may occur during storage.

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